

In the Claims

1. (currently amended) An apparatus comprising:
 a first die having channel and controller functions; and
 a second die having a buffer function, wherein the first and second dies are packaged together in ~~the~~ a single package and ~~the~~ pins of the single package connect to the first die and the second die.
2. (currently amended) The ~~drive apparatus~~ of claim 1, wherein the second die comprises a synchronous dynamic random access memory in a known good die format.
3. (currently amended) The ~~apparatus~~ of claim 1, wherein the single package is a thin quad flat pack package.
4. (currently amended) The ~~apparatus~~ of claim 1, wherein the single package is a ball grid array package.
5. (original) A computer system, comprising:
 a disc drive;
 a first die having a buffer function;
 a second die having a controller and channel function;
 wherein the first die is connected to the second die and wherein the first die and second die are packaged in a single package.
6. (original) The system of claim 5, wherein the buffer function comprises a synchronous dynamic random access memory in a known good die format.
7. (original) The system of claim 5, wherein the single package is a thin quad flat pack package.

8. (original) The system of claim 5, wherein the single package is a ball grid array package.
9. (original) The system of claim 5, wherein the single package is placed on a printed circuit board of the disc drive.
10. (original) The system of claim 5, wherein the first die and the second die are connected by interconnects.
11. (original) A method of making a disc drive for a computer system, comprising the steps of:
attaching a first die to a first area of a package;
attaching a second die to a second area of the package;
connecting the first die and second die with interconnects;
wherein the first die includes a buffer function for the disc drive; and
wherein the second die includes a controller function and a channel function for the disc drive.
12. (original) The method of claim 11, wherein the buffer function comprises a synchronous dynamic random access memory in a known good die format.
13. (original) The method of claim 11, wherein the package is a thin quad flat pack package.
14. (original) The method of claim 11, wherein the package is a ball grid array package.
15. (original) The method of claim 11, wherein the package is placed on a printed circuit board of the disc drive.